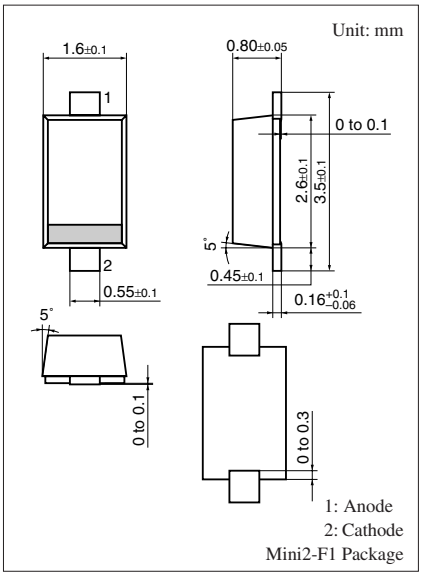
MA22D28

Silicon epitaxial planar type

For high speed switching



Marking Symbol: 3Z

■ Features

- Forward current $I_{F(AV)}$ = 1.5 A rectification is possible
- Low forward voltage V_F

■ Absolute Maximum Ratings $T_a = 25°C$

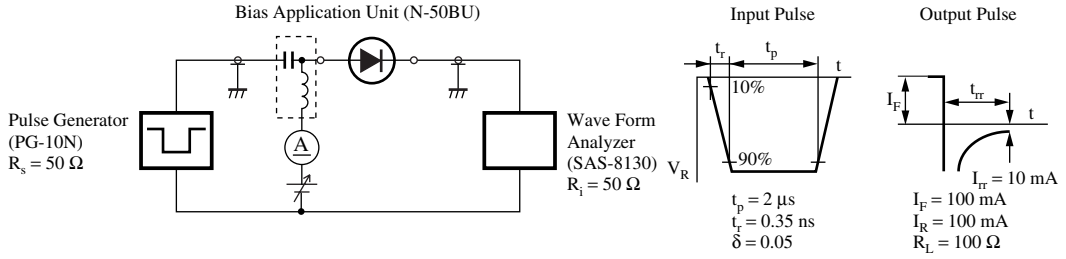
Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	30	V
Repetitive peak reverse voltage	V_{RRM}	30	V
Forward current (Average) *1	$I_{F(AV)}$	1.5	A
Non-repetitive peak forward surge current *2	I_{FSM}	30	A
Junction temperature	T_j	150	°C
Storage temperature	T_{stg}	−55 to +150	°C

Note) ∗1: Mounted on a alumina PC board
∗2: The peak-to-peak value in one cycle of 50 Hz sine wave (non-repetitive)

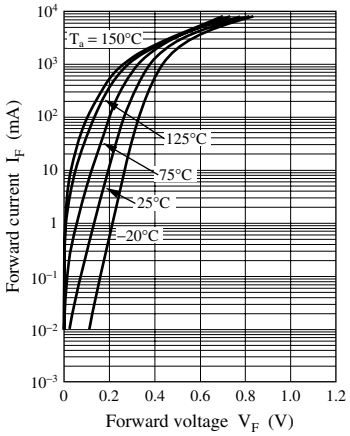
■ Electrical Characteristics $T_a = 25°C \pm 3°C$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_{F1}	I_F = 0.5 A		0.34	0.38	V
	V_{F2}	I_F = 1.0 A		0.38	0.42	
	V_{F3}	I_F = 1.5 A		0.42	0.46	
Reverse current	I_R	V_R = 30 V			100	µA
Terminal capacitance	C_t	V_R = 10 V, f = 1 MHz		50		pF
Reverse recovery time *	t_{rr}	$I_F = I_R$ = 100 mA I_{rr} = 10 mA , R_L = 100 Ω		13		ns

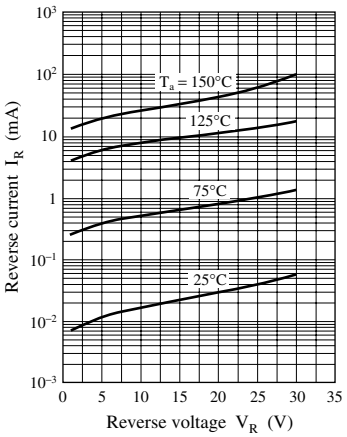
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
3. ∗: t_{rr} measuring instrument



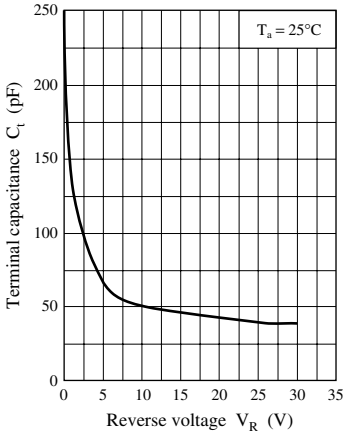
I_F — V_F



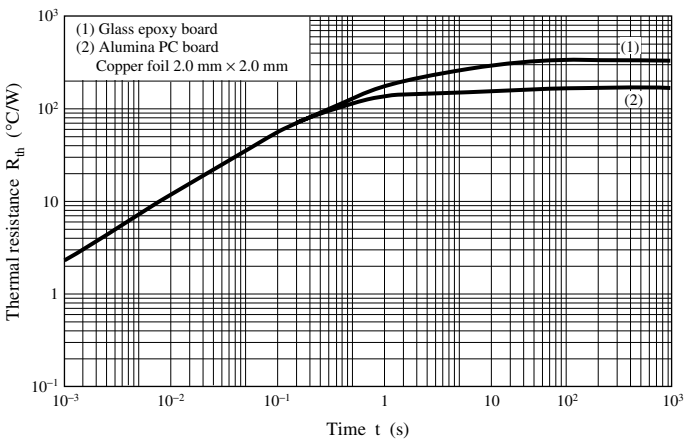
I_R — V_R



C_t — V_R



R_{th} — t



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